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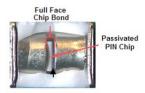




Rev. V3

Features

- Non-Magnetic Package Suitable for MRI Applications
- ♦ Rectangular MELF SMQ Ceramic Package
- ♦ Hermetically Sealed
- Low Rs for Low Series Loss
- Long τ_L for Lower Intermodulation Distortion
- ♦ Low C_i for High Series Isolation
- High Average Incident Power Handling
- RoHS Compliant



Diode Cross Section

1072

Description

The MA4P7452F-1072T is a surface mountable PIN diode in a non-magnetic, Metal Electrode Leadless Faced (MELF) package. The device incorporates M/A-COM Technology Solutions time proven HIPAX technology to produce a low inductance ceramic package with no ribbons or whisker wires. Incorporated in the package is a hard glass passivated, CERMACHIP™ PIN chip that is full face bonded on both the cathode and anode to maximize surface area for the lowest electrical and thermal resistance. The package utilizes a nonmagnetic plating process that provides for a package with extremely low permeability. MA4P7452F-1072T has been comprehensively characterized both electrically and mechanically to ensure repeatable and predictable performance. The non-magnetic MA4P7452F-1072T is the electrical equivalent of its magnetic counterpart the MA4P7002F-1072T.

Applications

This diode is well suited for use in low loss, low distortion, high power switching circuits and can be used in high magnetic field environments at HF through UHF frequencies. The low thermal resistance of this device provides excellent performance at high RF power incident levels, up to 100 watts CW. This device is designed to meet the most demanding electrical and mechanical MRI environments.

Designed for Automated Assembly

These SMQ PIN diodes are designed for high volume tape and reel assembly. The rectangular package design provides for highly efficient automatic pick and place assembly techniques. The parallel flat surfaces are suitable for key jaw or vacuum pickup. All solderable surfaces are tin plated and compatible with reflow and vapor phase soldering methods.

Absolute Maximum Ratings¹ @ 25°C

Parameter	Absolute Maximum	
Operating Temperature	-65 °C to +125°C	
Storage Temperature	-65 °C to +150°C	
Diode Junction Temperature	+175 °C Continuous	
Diode Mounting Temperature	+235°C for 10 seconds	
RF C.W. Incident Power	+ 50 dBm C.W.	
Forward D.C. Current	+ 250 mA	
Reverse D.C. Voltage @ -10uA	I - 150 V I	

^{1.} Exceeding these limits may cause permanent damage.



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Electrical Specifications @ +25 °C

Parameter	Symbol	Condition	Unit Value
Forward Voltage (Maximum)	V _F	I _F = +100 mA	1.0 V _{DC}
Voltage Rating (Minimum)	V _R	Ir = -10 uA	I – 150 I V _{DC}
Total Capacitance (Maximum)	Ст	-100 V @ 100 MHz	0.7 pF
Series Resistance (Maximum)	R _s	+100 mA @ 100 MHz	0.9 Ohms
Parallel Resistance (Minimum)	R_P	-10 V @ 100 MHz	75 K Ω
Carrier Lifetime (Nominal)	τι	+6 mA / -10 mA @ (50% - 90% Voltage)	9 µs
I-Region Length (Nominal)	μm	-	175 μm
C.W. Thermal Resistance (Maximum)	θ	I _H = 1A, I _L = 10 mA, T = 1 mS	15 °C/W
Power Dissipation in Free Air (Maximum)	W	I _F = +100 mA	4 W
Power Dissipation (Maximum)	P _D	I _F = +100 mA	10 W

Environmental Capability

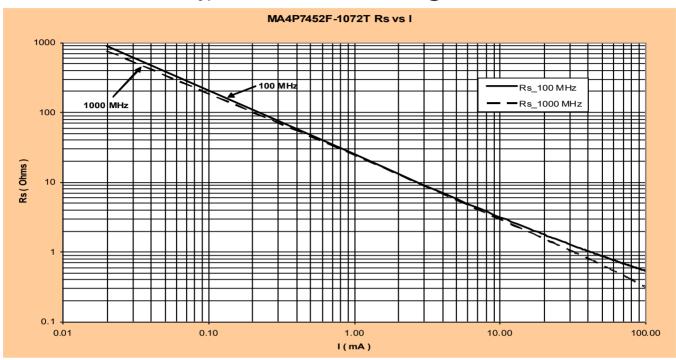
MELF devices are appropriate for use in industrial and military applications and can be screened to meet the environmental requirements of MIL-STD-750, MIL-STD-202 as well as other military standards. The table below lists some of the MIL-STD 750 tests the device is designed to meet.

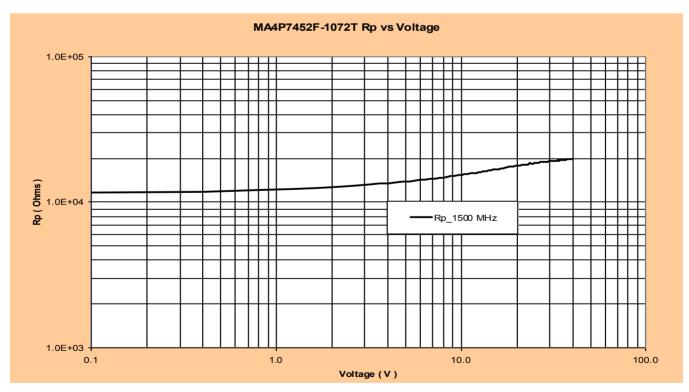
Test	Method	Description	
High Temperature Storage	1031	+150°C, for 340 Hours	
Temperature Shock	1051 -65°C to +150°C, 20 Cycles		
HTRB	1038	80% of rated V _B , +150°C, for 96 Hours	
Moisture Resistance	1021	No Initial Conditioning, 85% RH, +85°C	
Gross Leak	1071 Cond. E	Dye Penetrant Visual	
Vibration Fatigue	2046	20,000G's, 60Hz, x, y, z axis	
Solderability	2026	Test Temperature = +245°C	



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Typical Electrical Performance @ +25°C

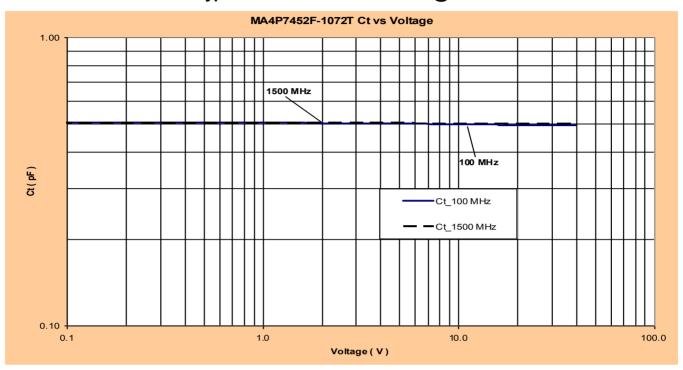


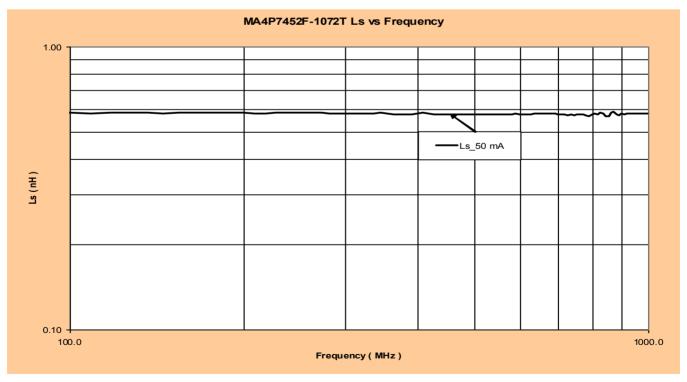




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Typical Electrical Performance @ +25°C

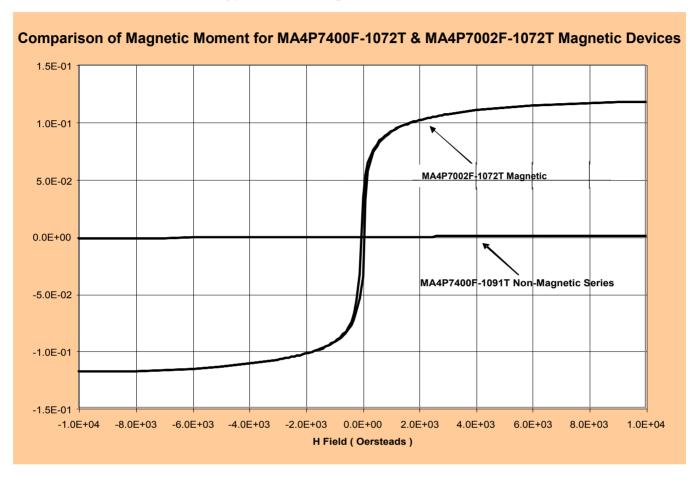






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Typical Non-Magnetic Performance



Typical Magnetic Properties of Non-Magnetic MA4P7452F-1072T Device vs.

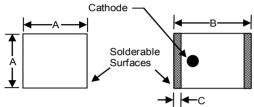
Conventional MA4P7002F-1072T Magnetic Device

Magnetic Property	MA4P7452F-1072T	MA4P7002F-1072T
Saturation Moment (EMU) @ H = H _{MAX} Oersteads	2.3 x E-4	2.1 x E-2
Remanance Moment (EMU) @ H = 0 Oersteads	4.2 x E-8	7.1 x E-3
Coercivity (Oersteads) @ EMU = 0 Moment	1.0	59.2



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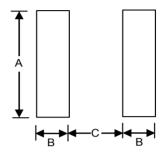
1072 MELF Surface Mount Package



↑	Solderable Surfaces
<u> </u>	→ ← c

Dimension	INCHES		мм	
	MIN.	MAX.	MIN.	MAX.
А	0.080	0.095	2.032	2.413
В	0.115	0.135	2.921	3.429
С	0.008	0.030	0.203	0.762
1072 Package (tape and reel only) 1500pcs/reel				

Circuit Pad Layout for 1072 MELF



Dimension	Package Style 1072	
	inches	mm
А	0.093	2.36
В	0.050	1.27
С	0.060	1.52

Ordering Information

Part Number	Package
MA4P7452F-1072T	Tape and Reel

MA4P7452F-1072T



Non Magnetic SMQ MELF PIN Diode

Rev. V3

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